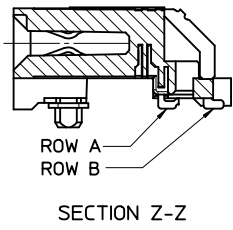
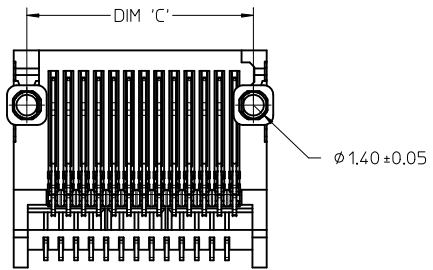
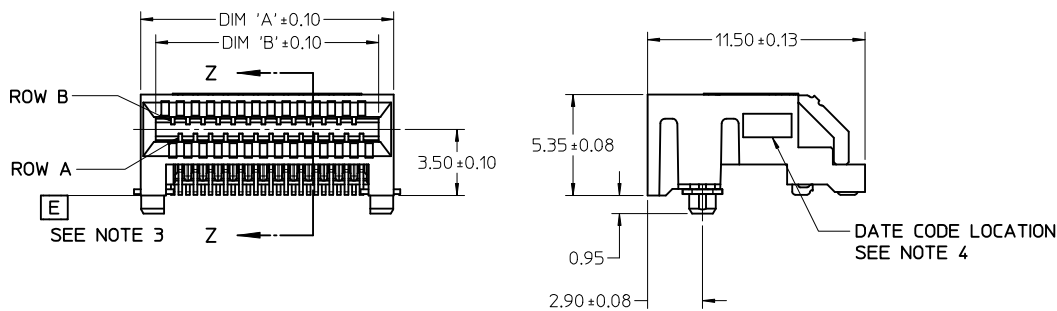
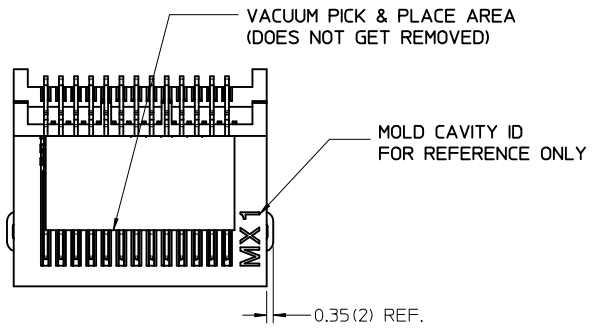
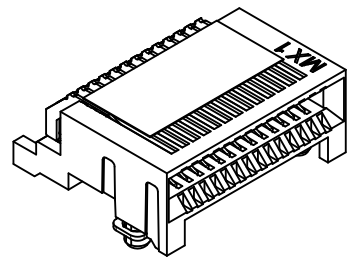


CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80



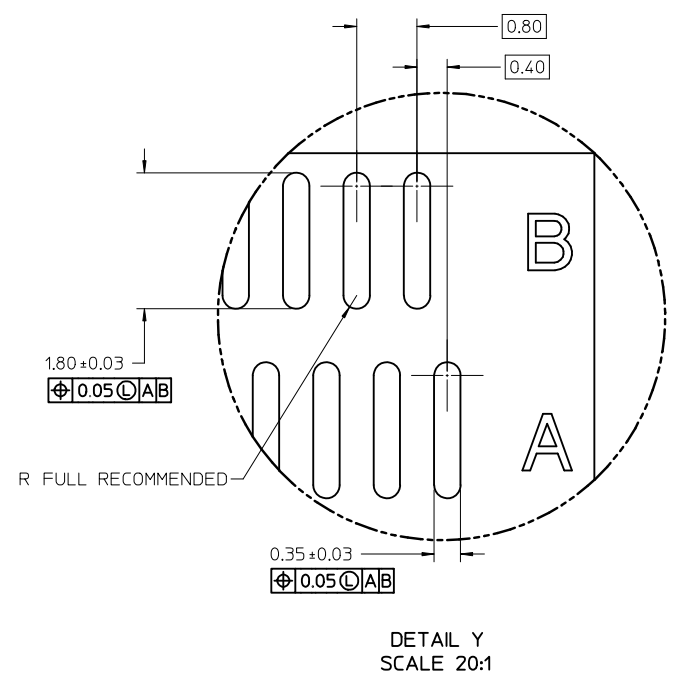
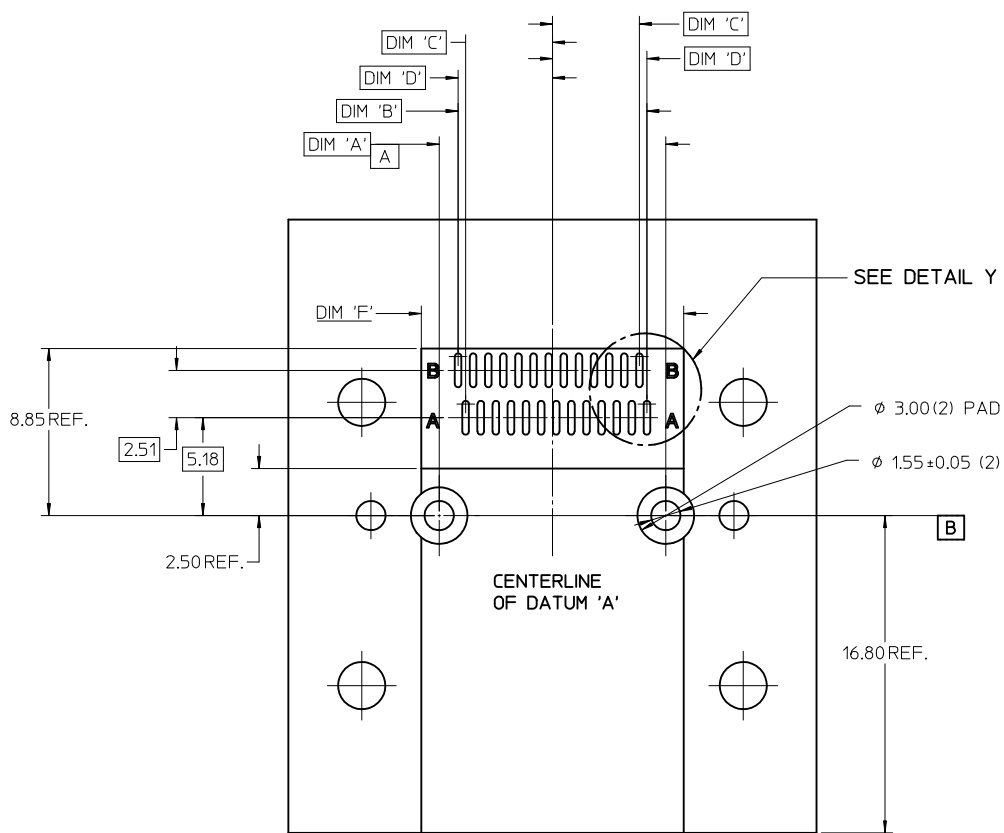
- NOTES
- MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK  
TERMINALS - COPPER ALLOY
  - PLATING:  
OPTION 1  
CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL  
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL.  
OPTION 2  
CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL  
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL.
  - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
  - DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
  - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
  - TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
  - TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
  - PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
  - CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
  - THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



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UPDATE VIEW SETS IEC NO: UCP2012-3302 IDRWN: GONZALEZ01 2012/04/20 CHKD: MCCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm	INCH	DRAWN BY	DATE	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING <b>molex</b> DOCUMENT NO. SD-75586-005 SHEET NO. 1 OF 6			
		3 PLACES ± --- ± ---			CHECKED BY	DATE				
		2 PLACES ± 0.13 ± ---			APPROVED BY	DATE				
1 PLACE ± 0.25 ± ---			DATE	DATE						
0 PLACE ± ±			MATERIAL NO. SEE CHART							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

# MOTHERBOARD FOOTPRINT RECOMMENDATION

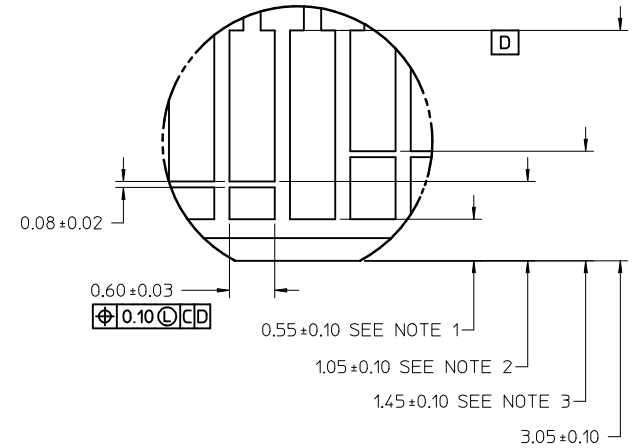
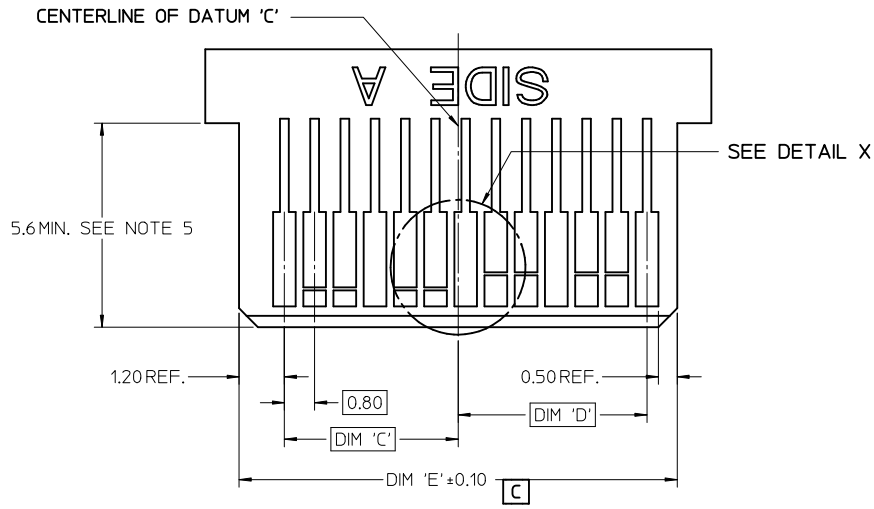


NOTES:  
1. SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

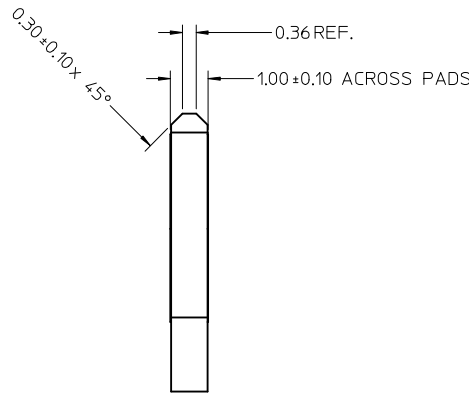
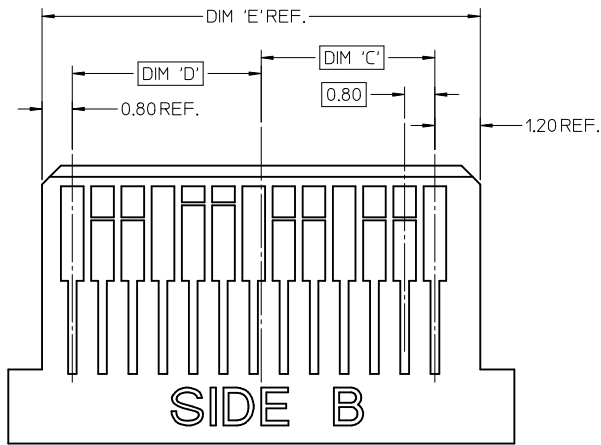
CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS					
		PAG TO PEG	FIRST PAD TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH	CONNECTOR WIDTH
		DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1 EC NO: UCP2012-3302 DRWN: GONZALEZ01 2012/04/20 CHKD: MCCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm INCH	MM ONLY	10:1	METRIC		
		4 PLACES ± --- ± ---	DRAWN BY DATE	IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING <b>molex</b> DOCUMENT NO. SD-75586-005 SHEET NO. 2 OF 6			
		3 PLACES ± --- ± ---	CHECKED BY DATE				
	2 PLACES ± 0.13 ± ---	APPROVED BY DATE					
	1 PLACE ± 0.25 ± ---	MATERIAL NO.					
	0 PLACE ± ±	ANGULAR ±1/2°	SEE CHART				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

# MODULE BOARD FOOTPRINT RECOMMENDATION



DETAIL X  
SCALE 20:1



NOTES:

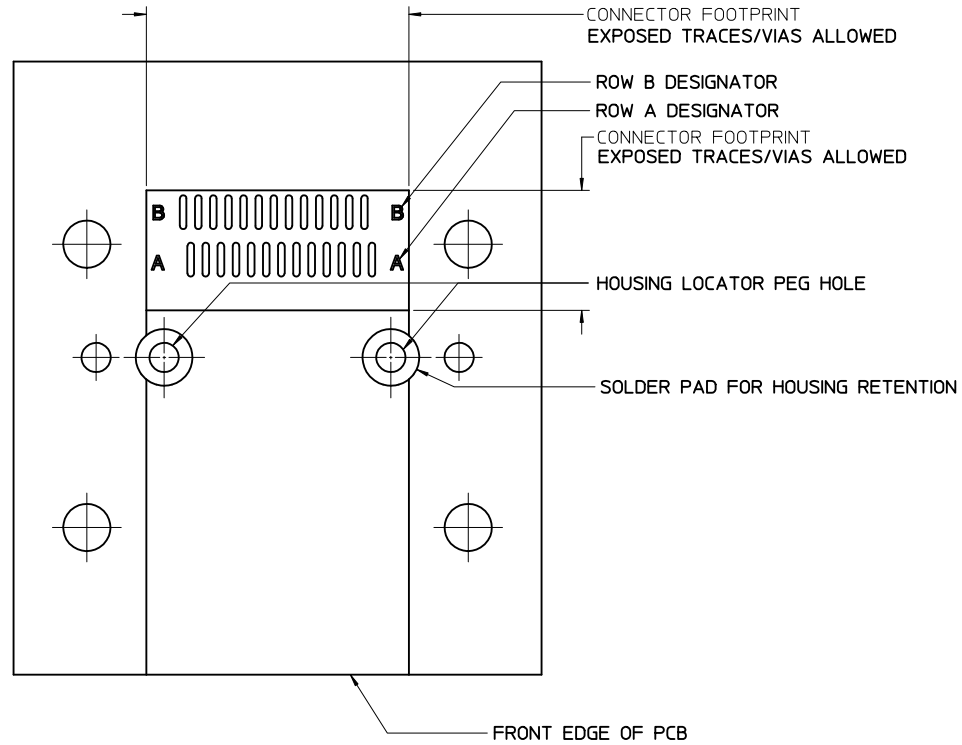
- PAD CONFIGURATION FOR FIRST MATE.
- PAD CONFIGURATION FOR SECOND MATE.
- PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
- FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
- MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TOUNGE.

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CIRCUIT SIZE	TERM/SIDE 'N'	MODULE BOARD WIDTH		
		CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
		DIM 'C'	DIM 'D'	DIM 'E'
26	13	4.60	5.00	11.60
38	19	7.00	7.40	16.40
68	34	13.00	13.40	28.40

SEE SHEET 1 EC NO: UCP2012-3302 DRAWN: GONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY KLANG		DATE 12/06/2006	
		4 PLACES ± --- ± ---				CHECKED BY JSWENSON		DATE 12/06/2006	
		3 PLACES ± --- ± ---				APPROVED BY MBANAKIS		DATE 12/06/2006	
2 PLACES ± 0.13 ± ---				MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
1 PLACE ± 0.25 ± ---				ANGULAR ± 1/2°		SEE CHART		SD-75586-005	
0 PLACE ± ±				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		3 OF 6	

# CONNECTOR FOOTPRINT ZONE IDENTIFICATION



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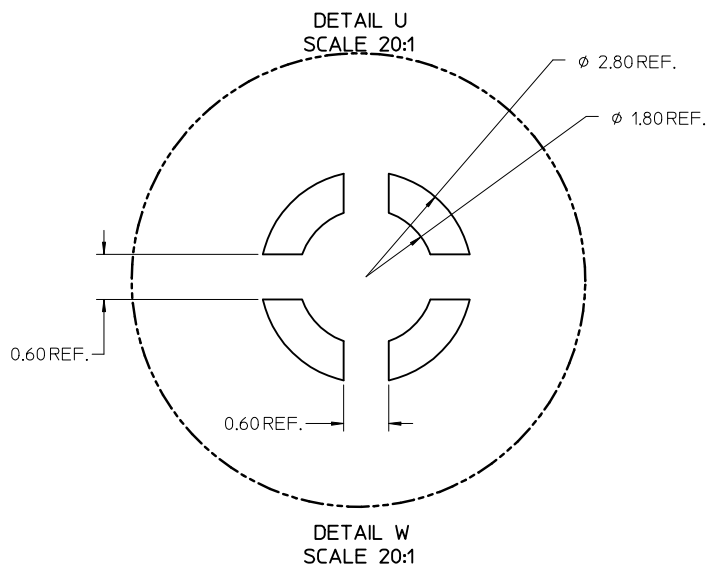
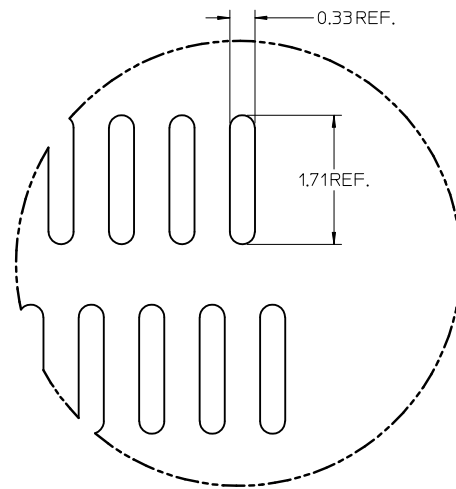
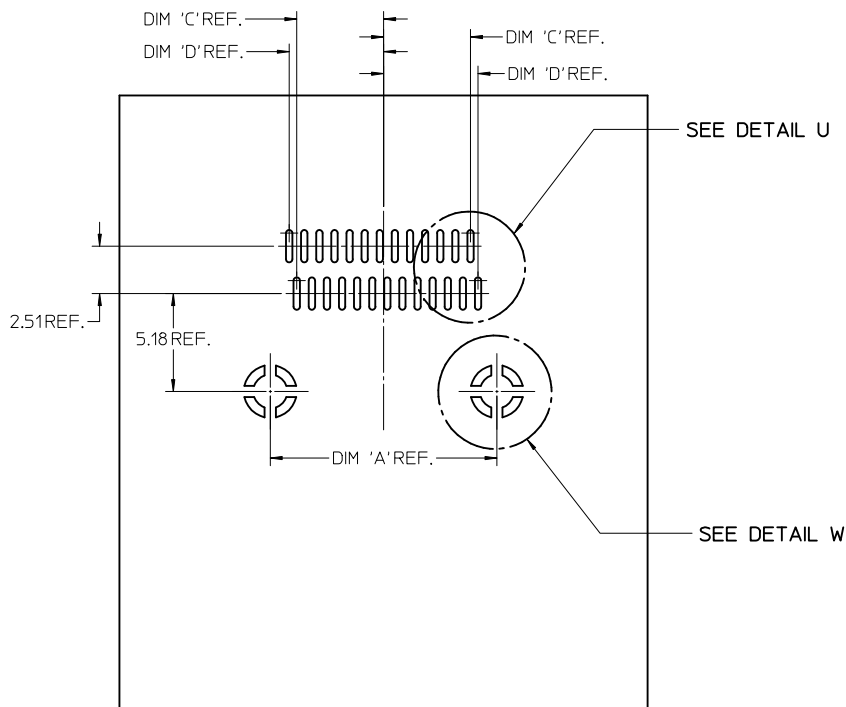
SEE SHEET 1 EC NO: UCP2012-3302 DRWN: JGONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>5:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
	▽=0	mm	INCH	DRAWN BY	DATE	TITLE <b>IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING</b>			
	▽=0	4 PLACES ± ---	± ---	KLANG	12/06/2006				
	▽=0	3 PLACES ± ---	± ---	CHECKED BY	DATE	<b>molex</b> DOCUMENT NO. <b>SD-75586-005</b> SHEET NO. <b>4 OF 6</b>			
▽=0	2 PLACES ± 0.13	± ---	JWENSON	12/06/2006					
	1 PLACE ± 0.25	± ---	APPROVED BY	DATE	MATERIAL NO. <b>SEE CHART</b>				
	0 PLACE ±	±	MBANAKIS	12/06/2006					
		ANGULAR ±1/2°		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		C					

NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

# SOLDER STENCIL RECOMMENDATION

SOLDER FOOT: ~90% OF PAD  
 SOLDER RING: ~45% OF PAD

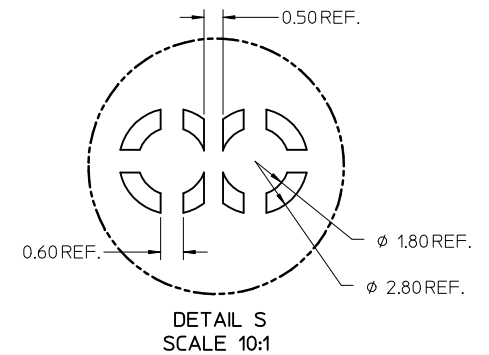
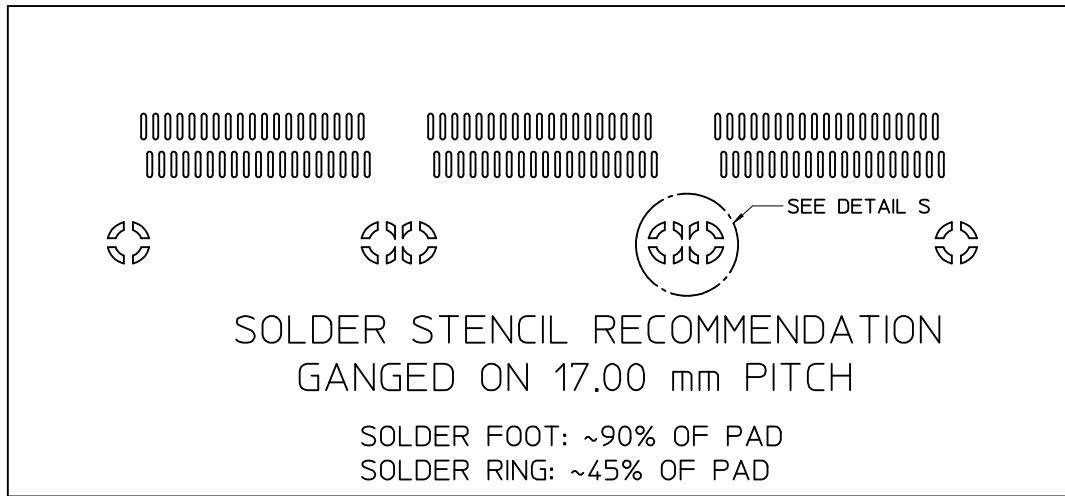
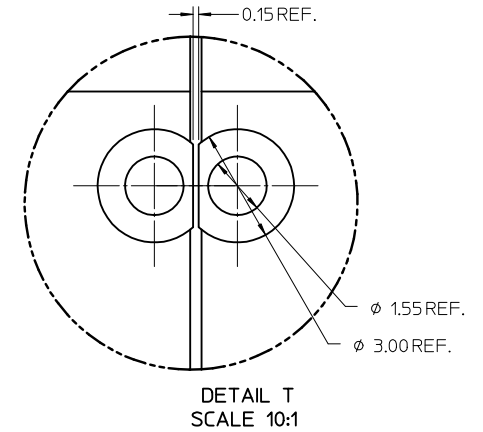
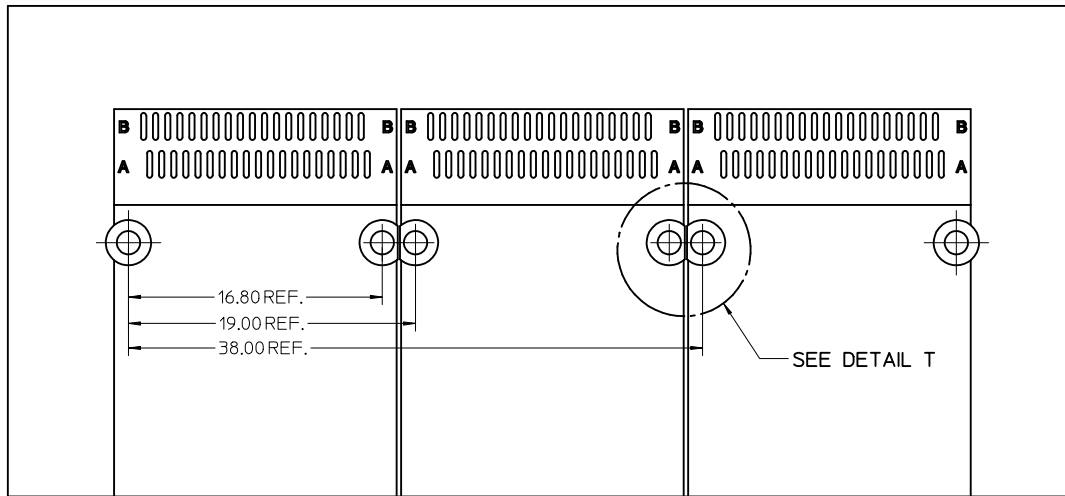


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CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS		
		DIM 'A'	DIM 'C'	DIM 'D'
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1 EC NO: UCP2012-3302 DRWN: JGONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± ±	DIMENSION STYLE MM ONLY DRAWN BY DATE KLANG 12/06/2006 CHECKED BY DATE JSWENSON 12/06/2006 APPROVED BY DATE MBANAKIS 12/06/2006	SCALE 5:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING <b>molex</b>	MATERIAL NO. SEE CHART DOCUMENT NO. SD-75586-005	SHEET NO. 5 OF 6	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ANGULAR ±1/2°	SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	REV C1							

# 38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



## NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

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SEE SHEET 1 EC NO: UCP2012-3302 DRWN: JGONZALEZ01 2012/04/20 CHKD: MCLELLAND 2012/05/30 APPR: MBANAKIS 2012/06/05	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>4:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY	DATE	TITLE		IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING <b>molex</b>	
4 PLACES ± ---	± ---	KLANG	12/06/2006	SEE CHART		DOCUMENT NO. <b>SD-75586-005</b>			
3 PLACES ± ---	± ---	CHECKED BY	DATE						SHEET NO. <b>6 OF 6</b>
2 PLACES ± 0.13	± ---	JSWENSON	12/06/2006	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
1 PLACE ± 0.25	± ---	APPROVED BY	DATE						
0 PLACE ±	±	MBANAKIS	12/06/2006						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		SIZE C					